

METHOD AND SYSTEM FOR APPLYING SOLDER PASTE

ABSTRACT OF THE DISCLOSURE

A method for applying solder paste to a circuit board includes covering a circuit board with a first stencil. The first stencil includes a first stencil hole. Solder paste is applied to a first area of the circuit board through the first stencil. The circuit  
5 board is then covered by a second stencil. The second stencil includes a second stencil hole and a void enclosure. The void enclosure covers the first area and prevents the second stencil from touching the first area. Solder paste is applied to a second area of the circuit board through the second stencil. The second stencil hole has a width greater than the first stencil hole in order to obtain different solder widths  
10 on the circuit board to accommodate components of different pitch sizes.